30V N-Channel Logic Level Enhancement Mode MOSFET

MTN2306N3

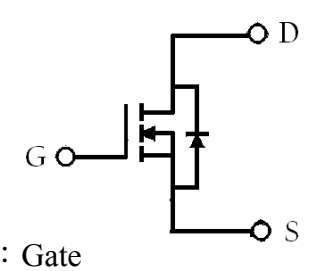
BV_{DSS}	30V
I_D	4.8A
$R_{DSON(TYP)}$@V_{GS}=10V, I_D=3.5A	35mΩ
$R_{DSON(TYP)}$@V_{GS}=4.5V, I_D=2A	58mΩ

Features

- Lower gate charge
- Pb-free lead plating and Halogen-free package

Equivalent Circuit

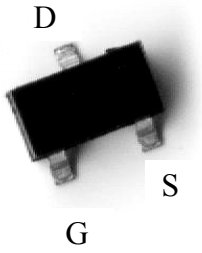
MTN2306N3



G：Gate
S：Source
D：Drain

Outline

SOT-23



Absolute Maximum Ratings (Tc=25°C, unless otherwise noted)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_A=25°C, V_{GS}=10V	I_D	4.8	A
	T_A=70°C, V_{GS}=10V		3.8	
Pulsed Drain Current		I_{DM}	20 (Note 1 & 2)	A
Power Dissipation	T_A=25°C	P_D	1.38 (Note 3)	W
	T_A=70°C		0.88 (Note 3)	
Thermal Resistance, Junction to Ambient		Rth, j-a	90 (Note 3)	°C/W
Operating Junction and Storage Temperature		Tj, Tstg	-55 ~ +150	°C

Note : 1. Pulse width limited by maximum junction temperature.
2. Duty cycle ≤ 1%.
3. Surface mounted on 1 in² copper pad of FR4 board, t≤10s; 270°C/W when mounted on min. copper pad.

Electrical Characteristics (T_A=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	30	-	-	V	V_{GS}=0, I_D=250μA
$V_{GS(th)}$	1	1.8	3	V	V_{DS}=V_{GS}, I_D=250μA
I_{GSS}	-	-	±100	nA	V_{GS}=±20V, V_{DS}=0
I_{DSS}	-	-	1	μA	V_{DS}=24V, V_{GS}=0
	-	-	10		V_{DS}=20V, V_{GS}=0, Tj=125°C
*$R_{DS(ON)}$ [1]	-	35	60	mΩ	I_D=3.5A, V_{GS}=10V
	-	58	90		I_D=2A, V_{GS}=4.5V
*G_{FS} [1]	-	5	-	S	V_{DS}=5V, I_D=3.5A
Dynamic					
Ciss	-	384	-	pF	V_{DS}=10V, V_{GS}=0, f=1MHz
Coss	-	46	-		
Crss	-	34	-		
*$t_{d(ON)}$ [1] [2]	-	4	-	ns	V_{DS}=10V, I_D=1A,V_{GS}=10V, R_G=6Ω
*t_r [1] [2]	-	3.7	-		
*$t_{d(OFF)}$ [1] [2]	-	8	-		
*t_f [1] [2]	-	3.5	-		
*Qg [1] [2]	-	6	-	nC	V_{DS}=10V, I_D=4.8A, V_{GS}=4.5V
*Qgs [1] [2]	-	1.5	-		
*Qgd [1] [2]	-	1.7	-		
Source-Drain Diode					
I_S	-	-	2	A	
I_{SM} [3]	-	-	8		
V_{SD} [1]	-	0.85	1.2	V	I_F=I_S, V_{GS}=0V

[1] Pulse test : Pulse width≤300μs, Duty cycle≤2%

[2] Independent of operating temperature

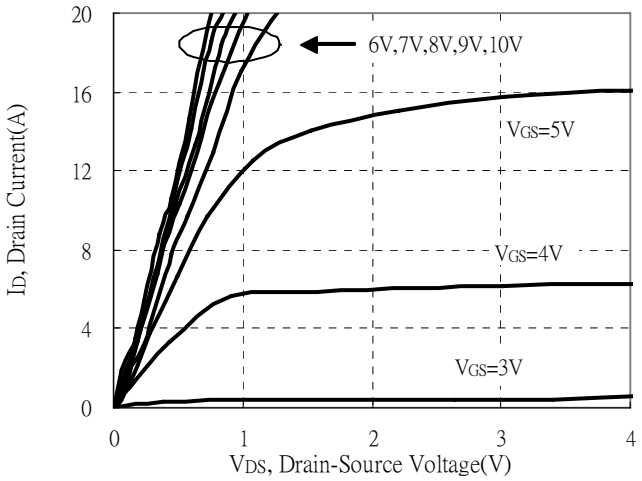
[3] Pulse width limited by maximum junction temperature

Ordering Information

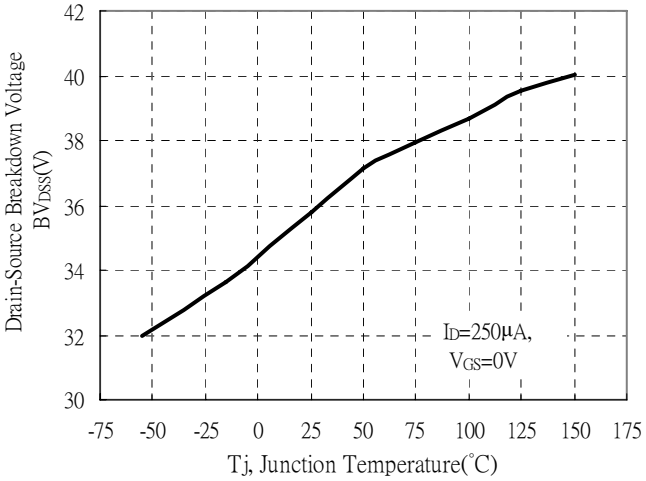
Device	Package	Shipping	Marking
MTN2306N3	SOT-23 (Pb-free)	3000 pcs / Tape & Reel	2306

Typical Characteristics

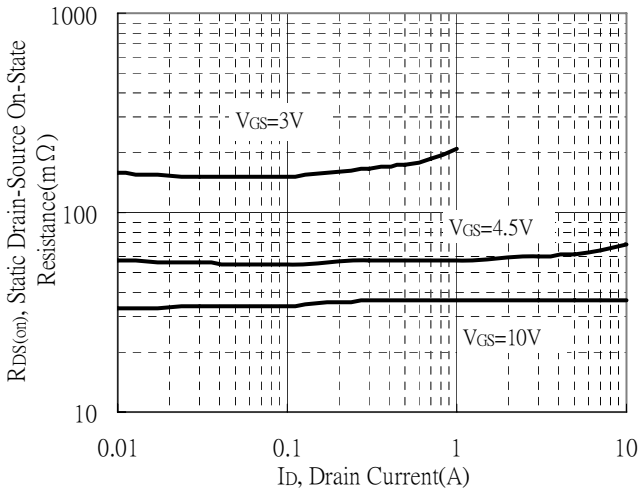
Typical Output Characteristics



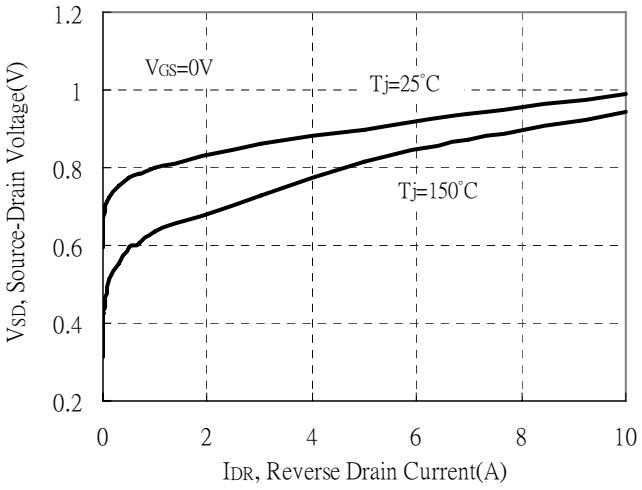
Brekdown Voltage vs Ambient Temperature



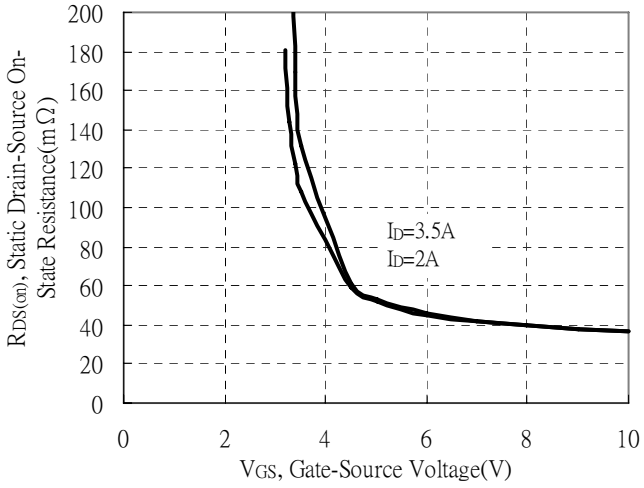
Static Drain-Source On-State resistance vs Drain Current



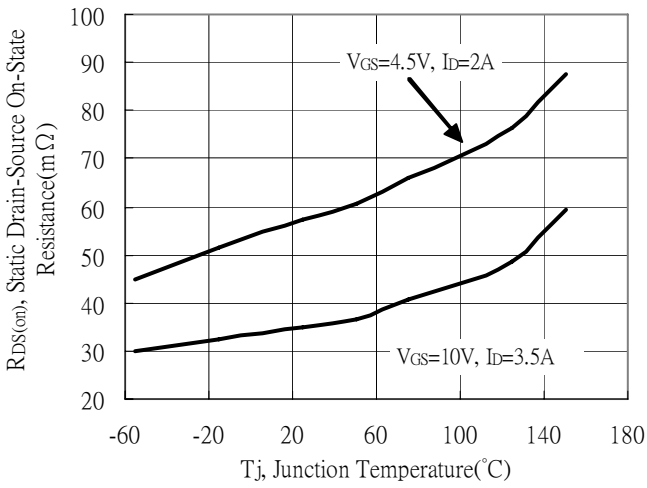
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

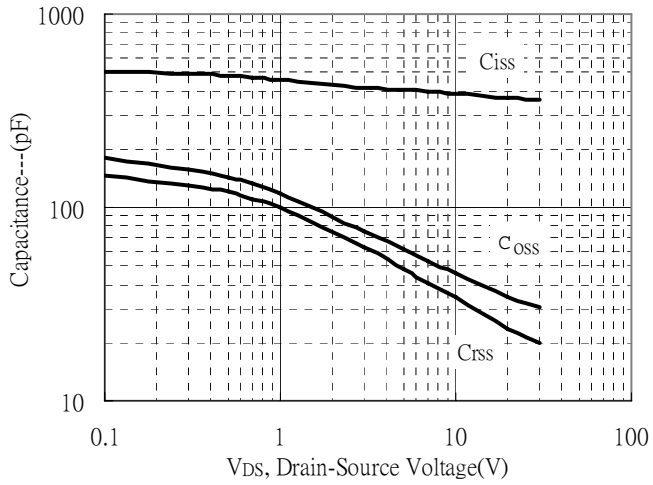


Drain-Source On-State Resistance vs Junction Tempearture

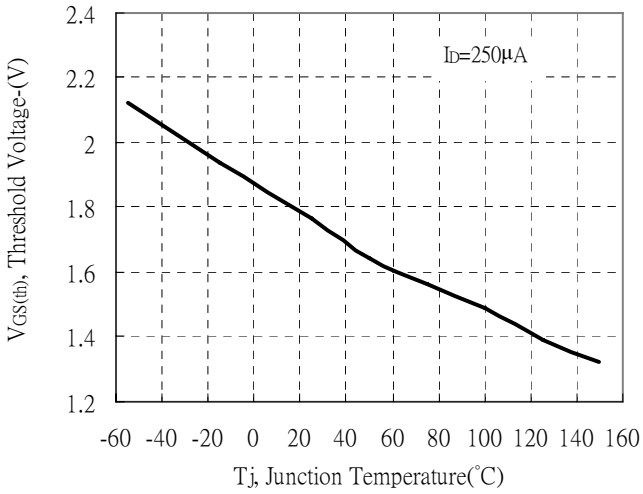


Typical Characteristics(Cont.)

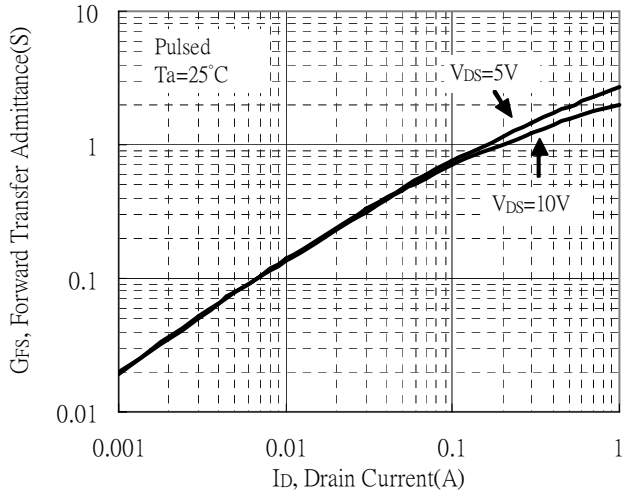
Capacitance vs Drain-to-Source Voltage



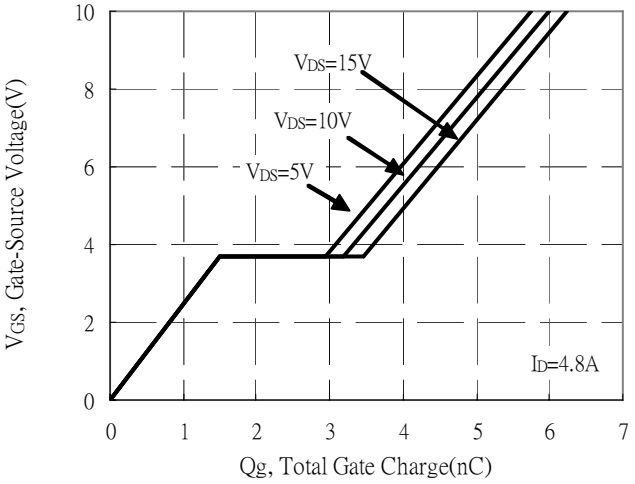
Threshold Voltage vs Junction Tempearture



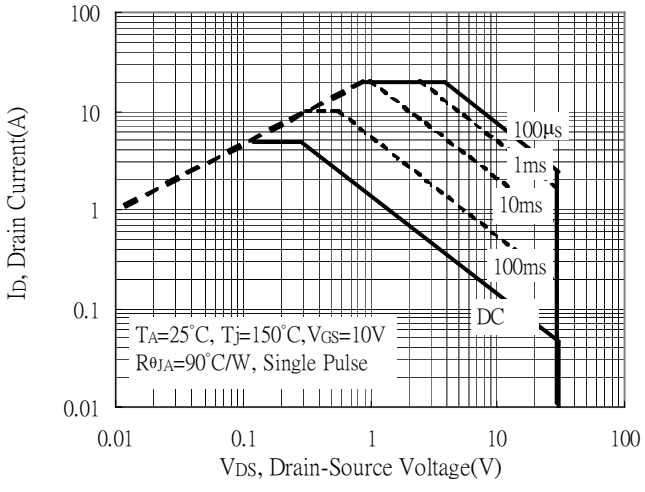
Forward Transfer Admittance vs Drain Current



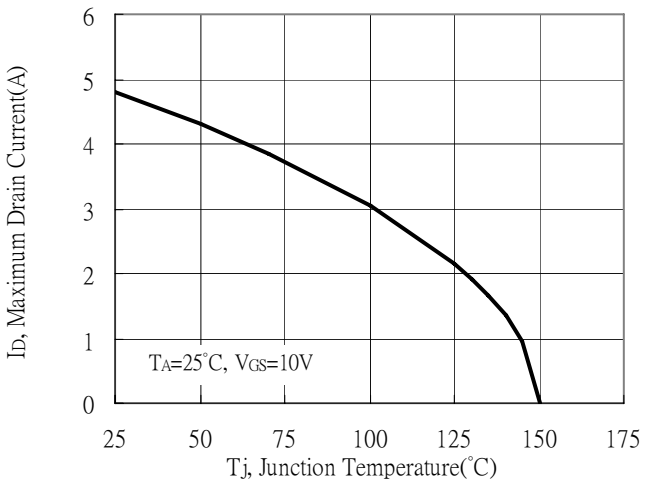
Gate Charge Characteristics



Maximum Safe Operating Area

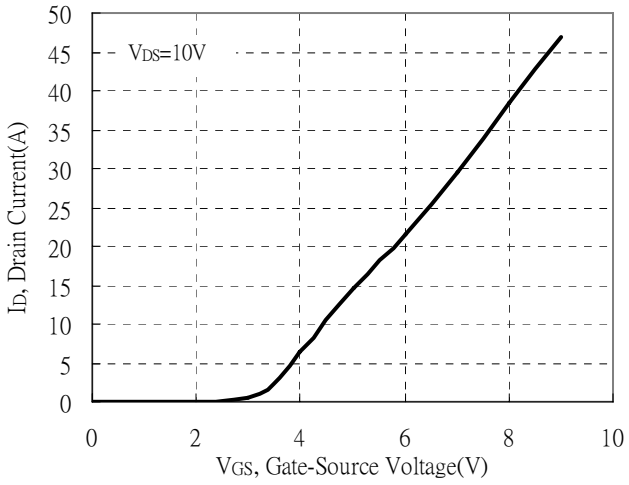


Maximum Drain Current vs JunctionTemperature

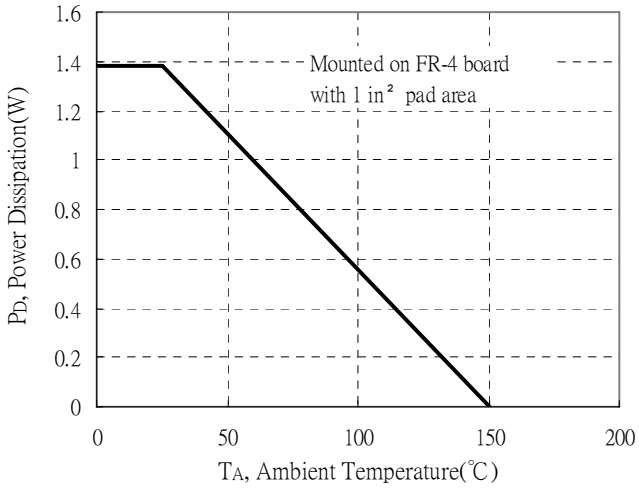


Typical Characteristics(Cont.)

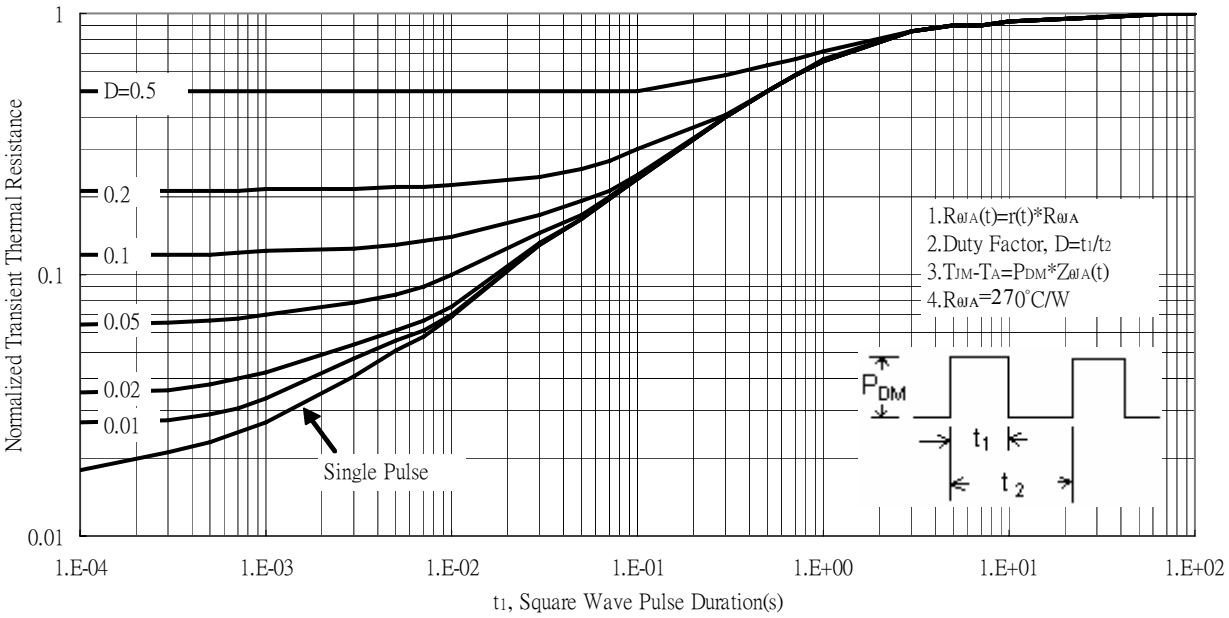
Typical Transfer Characteristics



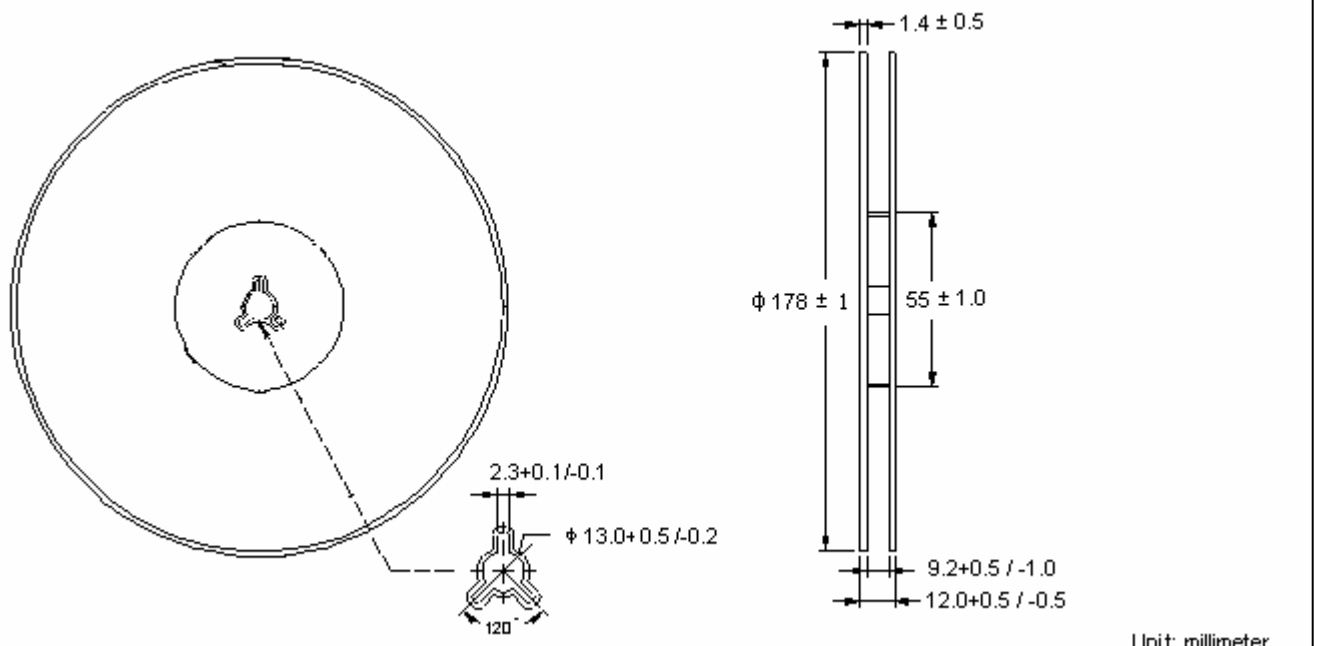
Power Derating Curve



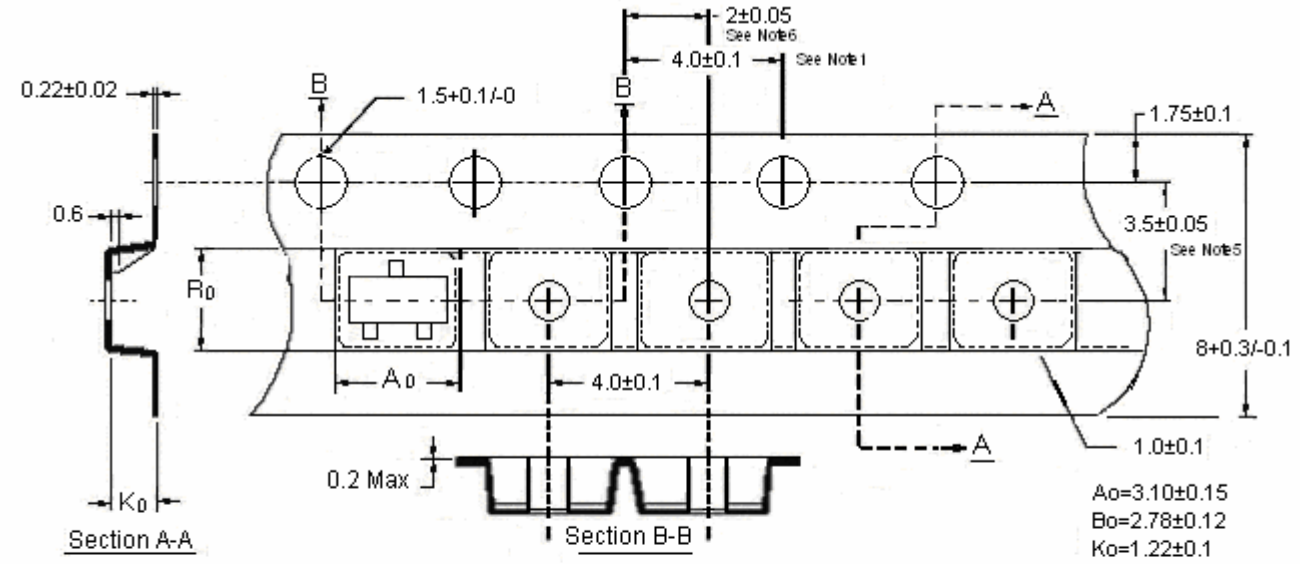
Transient Thermal Response Curves



Reel Dimension



Carrier Tape Dimension



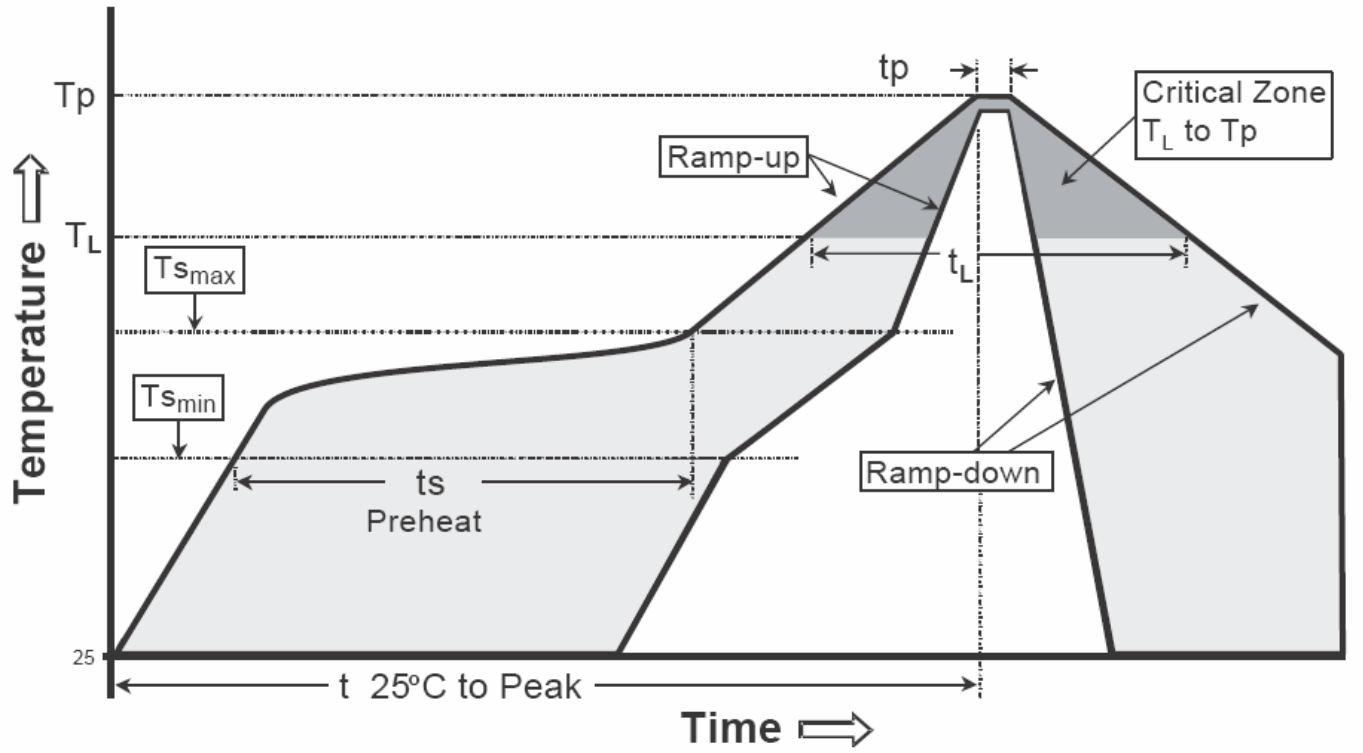
Notes:
1. 10 sprocket hole pitch cumulative tolerance ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material : conductive Black Polystyrene.
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

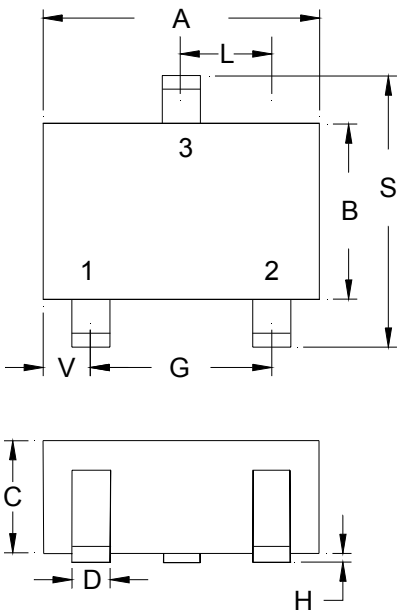
Recommended temperature profile for IR reflow



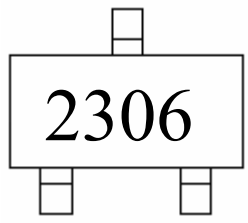
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(T_S min) −Temperature Max(T_S max) −Time($t_{s\ min}$ to $t_{s\ max}$)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) − Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-23 Dimension



Marking:



3-Lead SOT-23 Plastic
Surface Mounted Package
CYStek Package Code: N3

Style: Pin 1.Gate 2.Source 3.Drain

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0032	0.0079	0.08	0.20
B	0.0472	0.0669	1.20	1.70	K	0.0118	0.0266	0.30	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1161	2.10	2.95
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0000	0.0040	0.00	0.10					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.